



Subject: Motorola PRODUCT AND PROCESS CHANGE NOTIFICATION 4492

TITLE: THE WHOLE SERIES OF MC33063A DIE FABRICATION AT ALLEGRO MICROSYSTEMS

EFFECTIVE DATE: 10-JUN-99

AFFECTED CHANGE CATEGORIES Subcontractor Fab Site

AFFECTED PRODUCT DIVISIONS GENERAL PURPOSE PRO

ADDITIONAL RELIABILITY DATA: Available Ref: RJJ930 Contact your local Motorola Sales Office.

SAMPLES: Contact Below Ref: R12646@email.sps.mot.com Contact your local Motorola Sales Office.

For any questions concerning this notification: REFERENCE:MOUAYED SALEH PHONE: 602-423-4946

DISCLAIMER:

MOTOROLA WILL CONSIDER THIS CHANGE APPROVED UNLESS SPECIFIC CONDITIONS OF ACCEPTANCE ARE PROVIDED IN WRITING WITHIN 30 DAYS OF RECEIPT OF THIS NOTICE. TO DO SO, CONTACT YOUR LOCAL MOTOROLA SALES OFFICE. GPCN FORMAT: CUSTOMER

DO NOT REPLY TO THIS MESSAGE.

Motorola Page:2 Semiconductor Products Sector PRODUCT AND PROCESS CHANGE NOTIFICATION

ISSUE DATE: 02-Mar-1999 EFFECTIVE DATE: 10-Jun-1999 NOTIFICATION #:4492 ISSUING DIVISION:PHX-GPPD

DESCRIPTION AND PURPOSE

Motorola Semiconductor Group (SCG) is pleased to announce the qualification of MC33063A series at Allegro Microsystems wafer fabrication located in Willow Grove, Pennsylvania, USA. The purpose of the qualification is wafer capacity expansion. The exact same masking layers of the mask set (B36E) are being used at the Allegro Microsystems as is presently used at the BPI wafer fab. The wafer process being used for the MC33063A series is standard linear, EPI 79 flow.

The Allegro wafer facility has been qualified and processing Motorola part types for several years. The MC34063A device qualification was performed by characterizing three wafer lots, and no significant change was found in the electrical characteristics.

QUALIFICATION PLAN

------LRE #1176 - Allegro Qual Device: SC77767 Package: 24 PDIP Technology: 85 EPI Die Size: 120x112 Assembly location: KLM \*Operating life TA= 150 Deg-C 504 HRS 1008 HRS A3 0/77 0/77 B3 0/77 0/77 C3 0/77 0/77 \*Temperature Cycle -65 Deg-C to +150 Deg-C 600 CYC 1000 CYC Α3 0/77 0/77 В3 0/77 0/77 C3 0/77 0/77 \*Autoclave (PTH) 15 PSIG; 121 Deg-C; 100% R.H. 96 HRS 240 HRS 0/45 0/45 Aб В6 0/45 0/45 0/45 0/45 C6 \*High Temp Storage TA=150 Deg-C 504 HRS 1008 HRS 0/77 A16 0/77 0/77 0/77 B16 0/77 C16 0/77 \*Solder Heat 260 Deg-C, 10 SEC ELECT A15 0/15 B15 0/15 C15 0/15

RELIABILITY DATA SUMMARY

The reliability data is covered by LRE #1176, and it's available upon request. The reliability test results are from the EPI 85 process at Allegro. Both EPI 85 and EPI 79 are considered the same technology, because of no significant wafer processing differences. A construction analysis of wafers fabricated using the EPI 79 process is available upon request. Motorola Page:3 Semiconductor Products Sector PRODUCT AND PROCESS CHANGE NOTIFICATION ISSUE DATE: 02-Mar-1999 NOTIFICATION #:4492 ISSUING DIVISION:PHX-GPPD EFFECTIVE DATE: 10-Jun-1999 ELECTRICAL CHARACTERISTIC SUMMARY \_\_\_\_\_ MC34063A @ 25 DEG-C Control-mean Std Dev Allegro-mean Std Dev Test \*Comp Threshold 1.248 0.003 1.248414 0.00219 (VTH, V) \*Comp Line Reg 0.840 0.659 0.72 0.5433 (VTH-Regline, mV) \*Charge Current -33.262 0.761 -32.926 0.5138 @ VCC=5v(ICHG1, uA) \*Discharge Current 218.020 4.557 214.958 2.1486 @VCC=5V(IDSCG1, uA) \*Discharge/Charge 6.556 0.136 6.53 0.1028 Ratio (IRATIO) \*VSAT Darlington 1.000 0.008 1.00761 0.00847 (VSAT1, V) \*OSC Frequency 32.152 0.585 30.072 0.5962 (F1 @VCC=5v, KHz) CHANGED PART IDENTIFICATION \_\_\_\_\_ Parts will be identified with Date Code 9930 or later.

FILE FORMAT: ASCII TEXT
FONT - Courier
SIZE - 12 Point
LINE - 70 characters/line
PAGE - 55 lines/page
PAGEBREAK CHARACTER - ^L (Control L)

AFFECTED DEVICE LIST (WITHOUT SPECIALS)

FMC33063AD	,	FMC34063ADR2	,	MC33063AD	,	MC33063ADR2
MC33063AP1	,	MC33063AVD	,	MC33063AVDR2	,	MC33063AVP